



SSOP-24

RoHS Compliance Document

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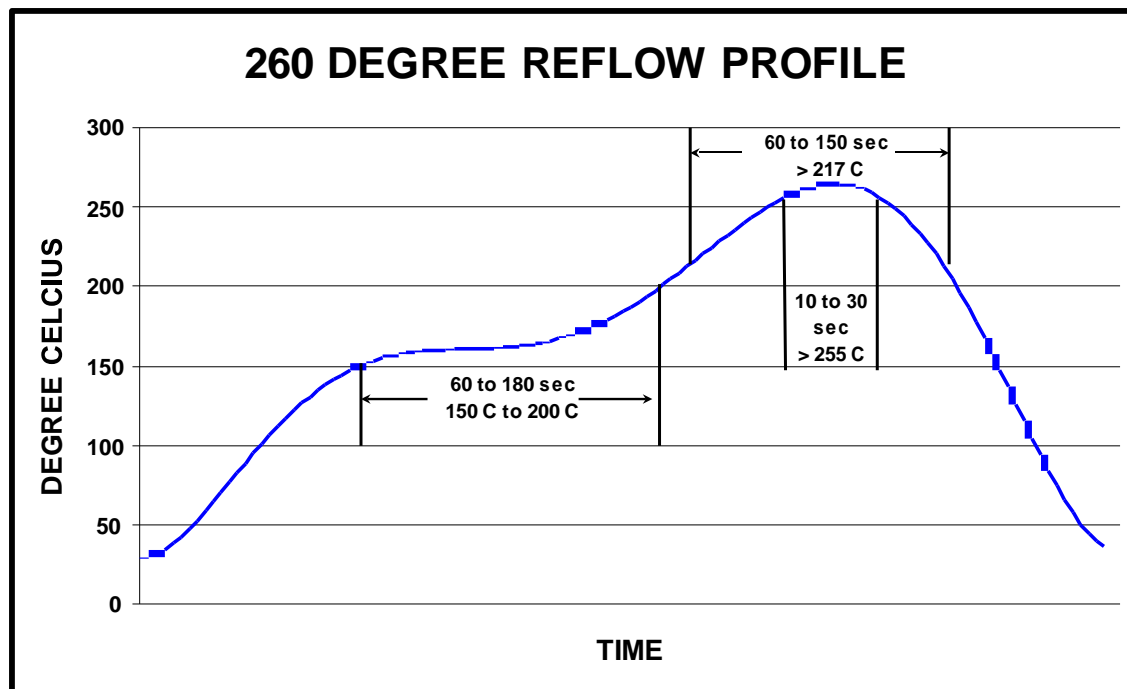
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Component	Material Name	Material Mass (g)	Element Name Composition	CAS #	Substance Mass (g)	Material Analysis Weight (%)	% of Total Weight
Chip	Silicon	0.00220	Si	7440-21-3	0.00220	100%	1.1%
Encapsulant	Epoxy Resin	0.11813	SiO ₂	7631-86-9	0.09450	80%	47.3%
			Epoxy	90598-46-2	0.01772	15%	8.9%
			Other	-	0.00591	5%	3.0%
Lead Frame	Copper	0.07500	Cu	7440-50-8	0.07275	97%	36.5%
			Ag	7440-22-4	0.00225	3%	1.1%
Die Attach	Silver Epoxy	0.00013	Ag	7440-22-4	0.00011	84%	0.1%
			Epoxy	90598-46-2	0.00002	16%	0.0%
Wire Bond	Gold	0.00043	Au	7440-57-5	0.00043	100%	0.2%
Lead Finish	Matte Tin*	0.00369	Sn	7440-31-5	0.00369	100%	1.8%

Total Weight
(g)

0.19958

*Tin whisker mitigation strategy is 150 °C, 1 hour anneal within 24 hours of tin plating.



This part is compliant with EU Directive 2002/95/EC (RoHS) and does not contain lead, mercury, cadmium (0.01%), hexavalent chromium, PBB or PBDE in concentrations greater than 0.1%, except as permitted by Annex (7).



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Test Definition	Test Conditions	Inspection Interval Class 1 and 2 Products	Total Duration Class 1 and 2 Products	Maximum Whisker Length (μm)
Room Temperature Humidity	30± 2°C/60± 3% RH	1000 hours	4000 hours	20
Temperature Humidity Unbiased	55± 3°C/85± 3% RH	1000 hours	4000 hours	20
Temperature Cycling	-40 to 55°C to 80 to 95°C, air to air, 10 min soak, approx 3	500 cycles	1500 cycles	45

Tin Whisker testing per JESD201, Environmental Acceptance Requirements for Tin Whisker Susceptibility of Tin and Tin Alloy Surface Finish

Tin Whisker Results (number of failing whiskers)

Test	1000 Hours	2000 Hours	3000 Hours	4000 Hours
Room Temperature Humidity Storage	0/24	0/24	0/24	0/24
Temperature Humidity	0/24	0/24	0/24	0/24
Test	500 Cycles	1000 Cycles	1500 Cycles	
Temperature Cycling	0/24	0/24	0/24	